



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 GHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITING	E.MURANO	Y.YAHIRO		K.H. KASHIWA

DESIGNATION

MM50-200B*-E1RE

SERIES PREFIX
シリーズ名

NO. OF CONTACTS
芯数

SOCKET TYPE
ソケットタイプ
B: LATCH TYPE SMT

KEYING TYPE (DETAIL A) 2: TYPE B (1.8V)
キタイプ
1: TYPE A (2.5V)

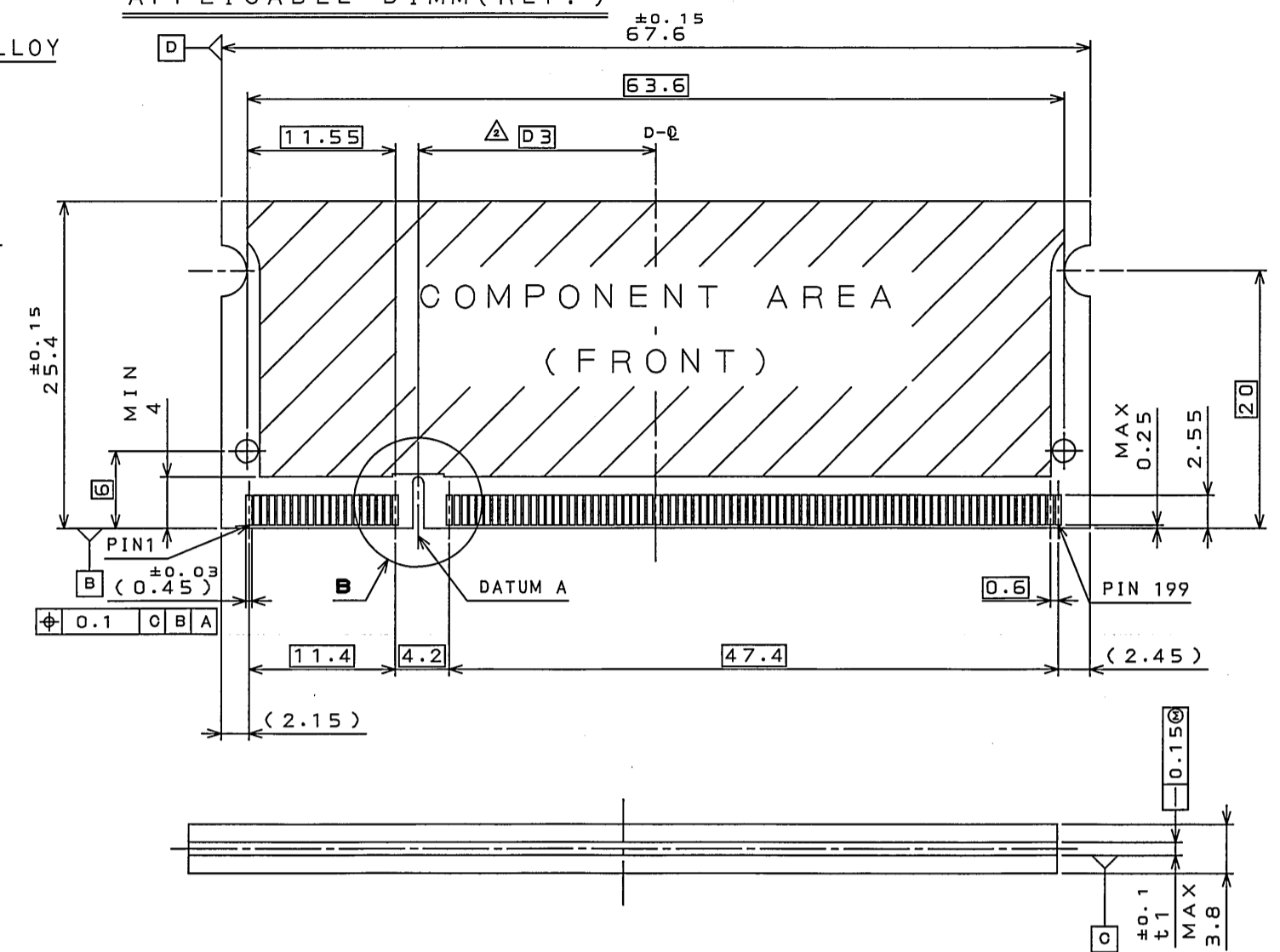
錫または錫合金(無鉛)
(LEAD FREE) TIN/TIN ALLOY

R: REVERSE
NONE: STANDARD

CONTACT FINISH
接点仕上げ
1: Au (0.1μm MIN) OVER NI

MODIFY CODE
モディファイコード
E: 6.5mm HEIGHT

APPLICABLE DIMM (REF.)



DETAIL A
(SCALE 5:1)
(REF. TABLE 1)

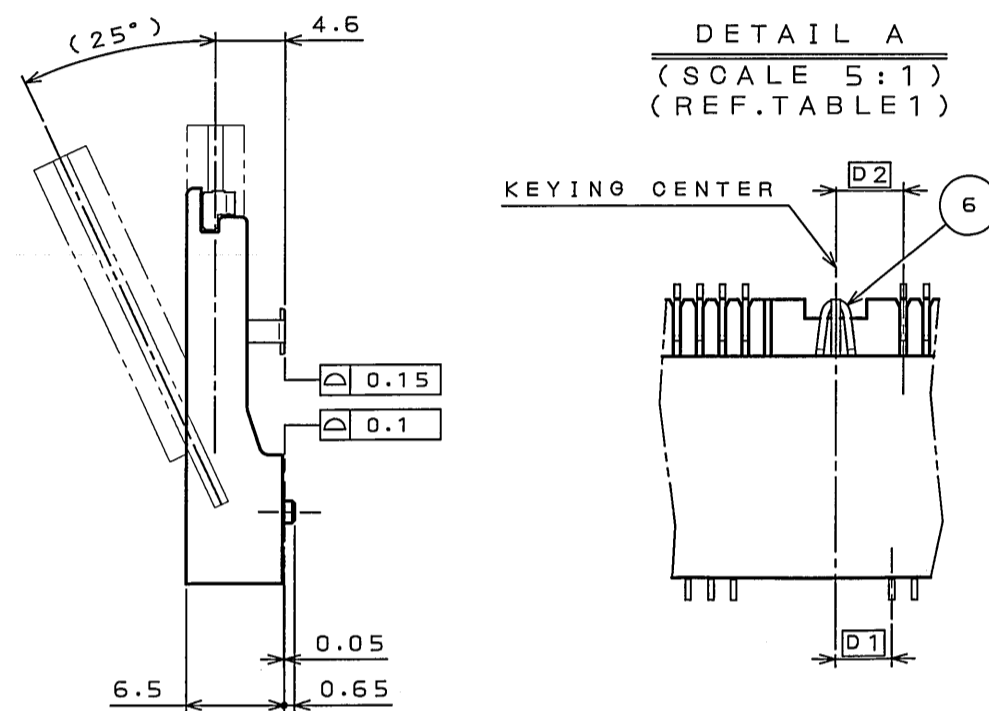


TABLE 2
DISCRIMINATION MARK

PARTS NAME	VOLTAGE MARK	ABRIDGED PART NUMBER
MM50-200B1-E1RE	2.5V	E1RE
MM50-200B2-E1RE	1.8V	2-E1RE

APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法(参考)

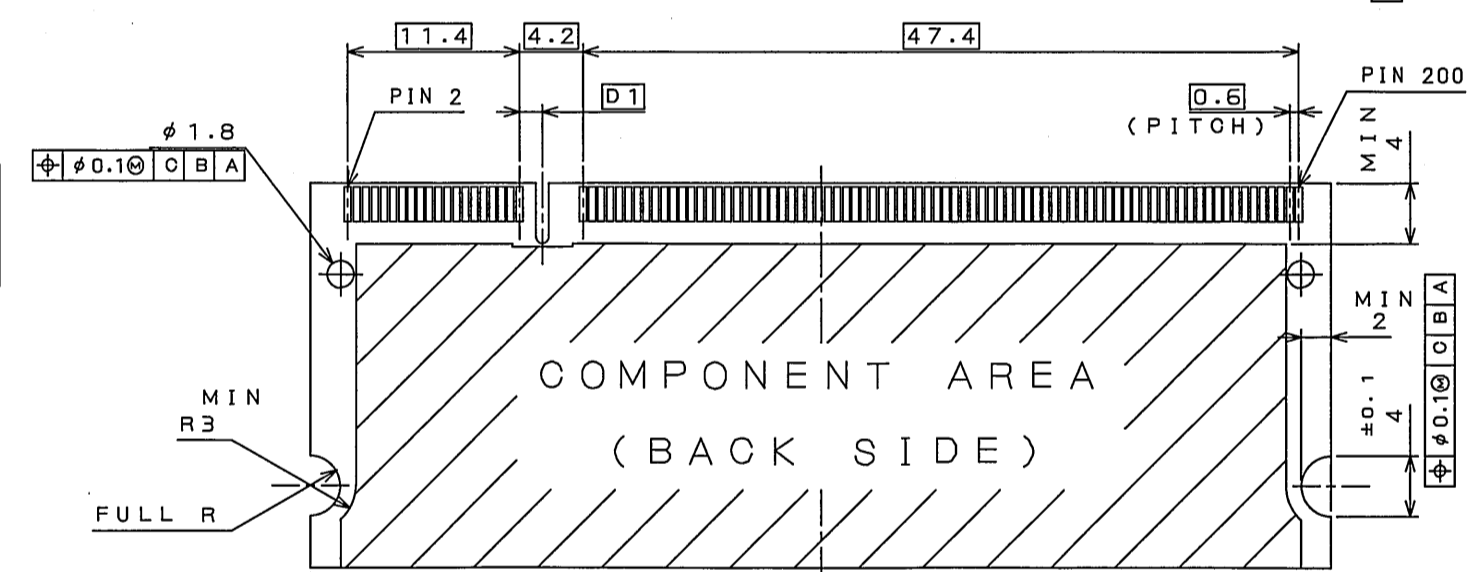
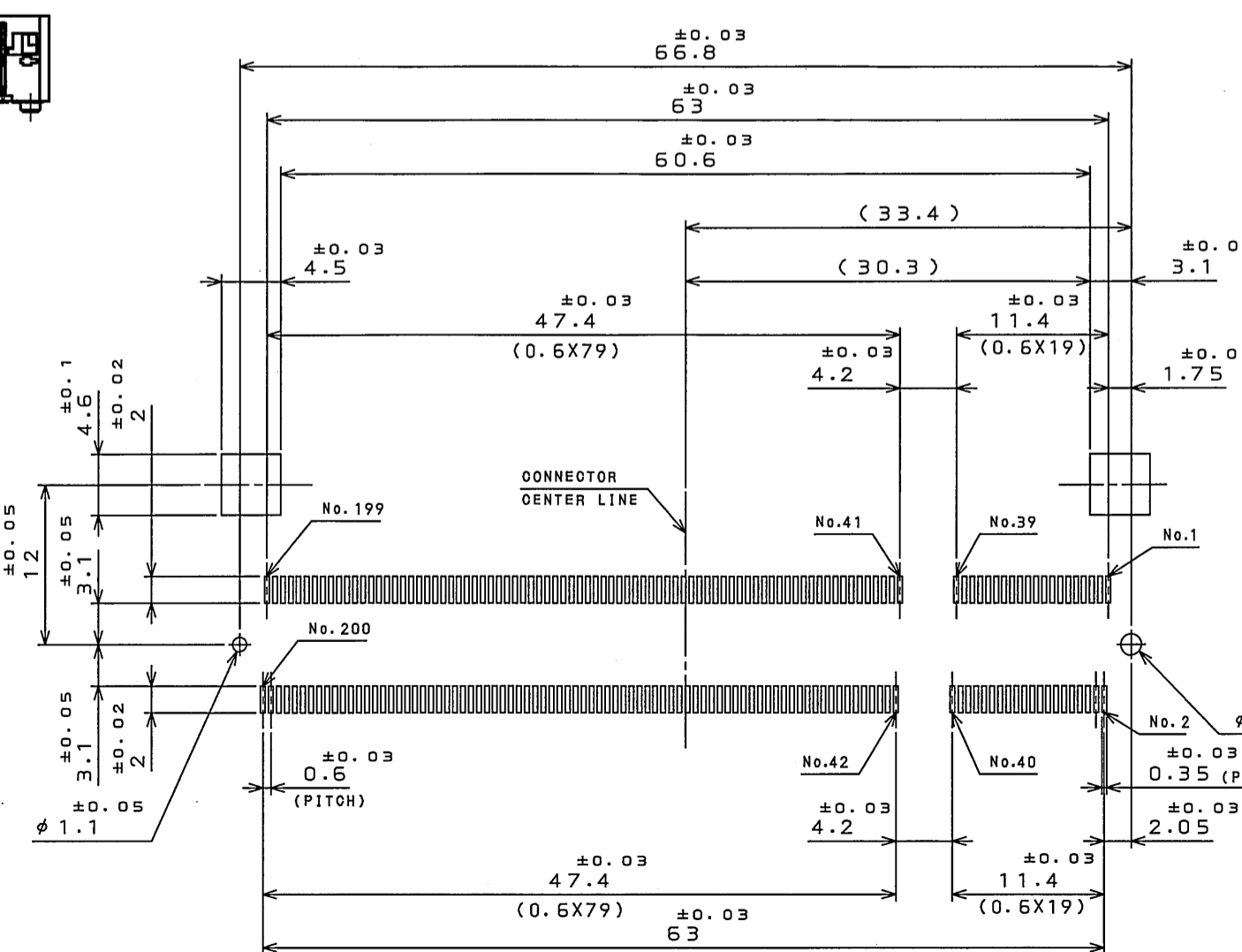
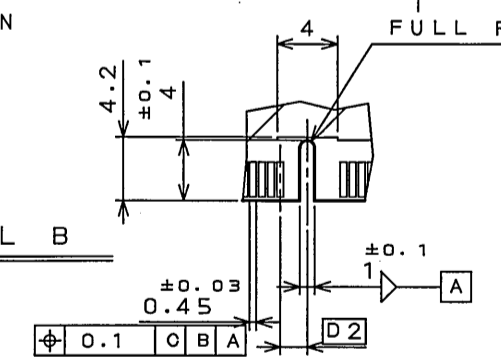


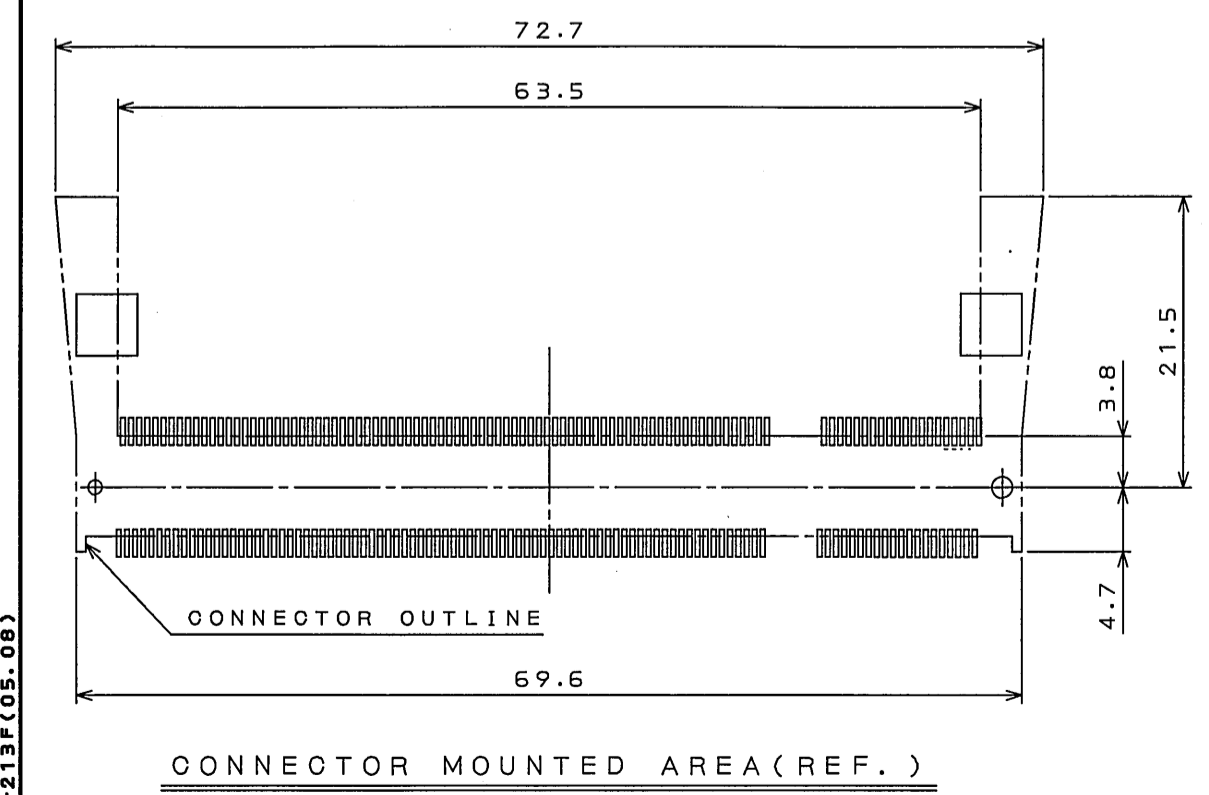
TABLE 1
MECHANICAL KEYING

POWER SUPPLY	D1	D2	D3
2.5V (TYPE A)	1.5	1.8	18.45
1.8V (TYPE B)	2.4	2.7	17.55

DETAIL B



6 KEY	1 STAINLESS		
5 HOLD DOWN 2	1 PHOSPHOR BRONZE TIN PLATING		
4 HOLD DOWN 1	1 PHOSPHOR BRONZE TIN PLATING		
3 INSULATOR	1 GLASS FILLED LOP		UL94 V-0 COLOR WHITE
2 BOTTOM SIDE CONTACT	100 PHOSPHOR BRONZE	CONTACT AREA: Au (0.1μm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	
1 TOP SIDE CONTACT	100 PHOSPHOR BRONZE	CONTACT AREA: Au (0.1μm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL
仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE)	尺度 (SCALE)
JACS-1655-01		20.May.2004	2:1
一般公差 (GENERAL TOLERANCE)		製図 DR.	名称 (TITLE)
寸法 (DIMENSION)		担当 GHK.	MM50
. ±0.8		Y.YAHIRO	-200B*-E1RE
.X ±0.4		承認 APPD.	
.XX ±0.1		S.KASHIWA	
.XXX ±			
質量 (MASS)		製図 DR.	備考 REMARKS
			日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
			図面番号 (DRAWING NO.)
			SJ101278
			版数 (REV.)
			2



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